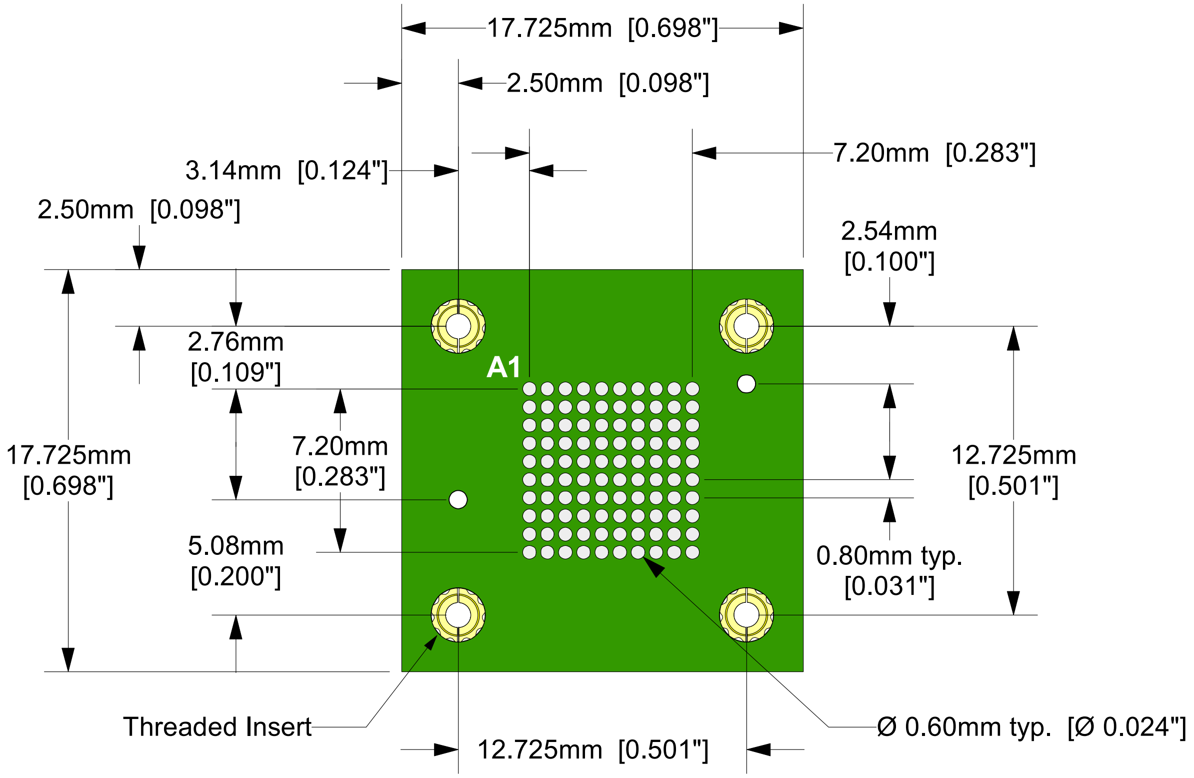
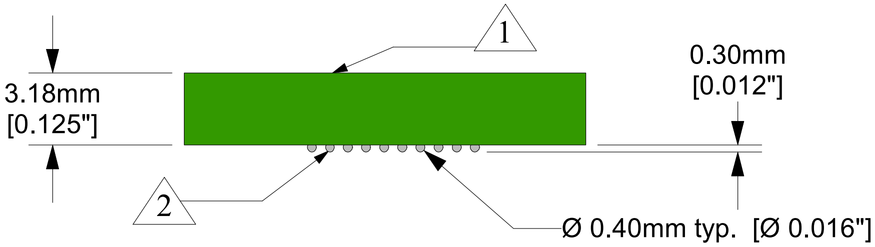
Top View



Side View



1 Substrate: 3.18mm ±0.025mm [0.125" ±0.001"] FR4/G10 or equivalent high temp material. 17µm [1/2 oz.] Cu clad. SnPb plating.

2 Solder ball: Eutectic Sn63Pb37

Description: BGA Surface Mount Adaptor
100 position surface mount land pattern to solder balls. To be used with GHz sockets.

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA100C-B-05 Drawing	Status: Released	Scale: 3:1	Rev: B
© 2002 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: H. Hansen File: SF-BGA100C-B-05 Dwg		Date: 8/14/02 Modified: 4/12/05